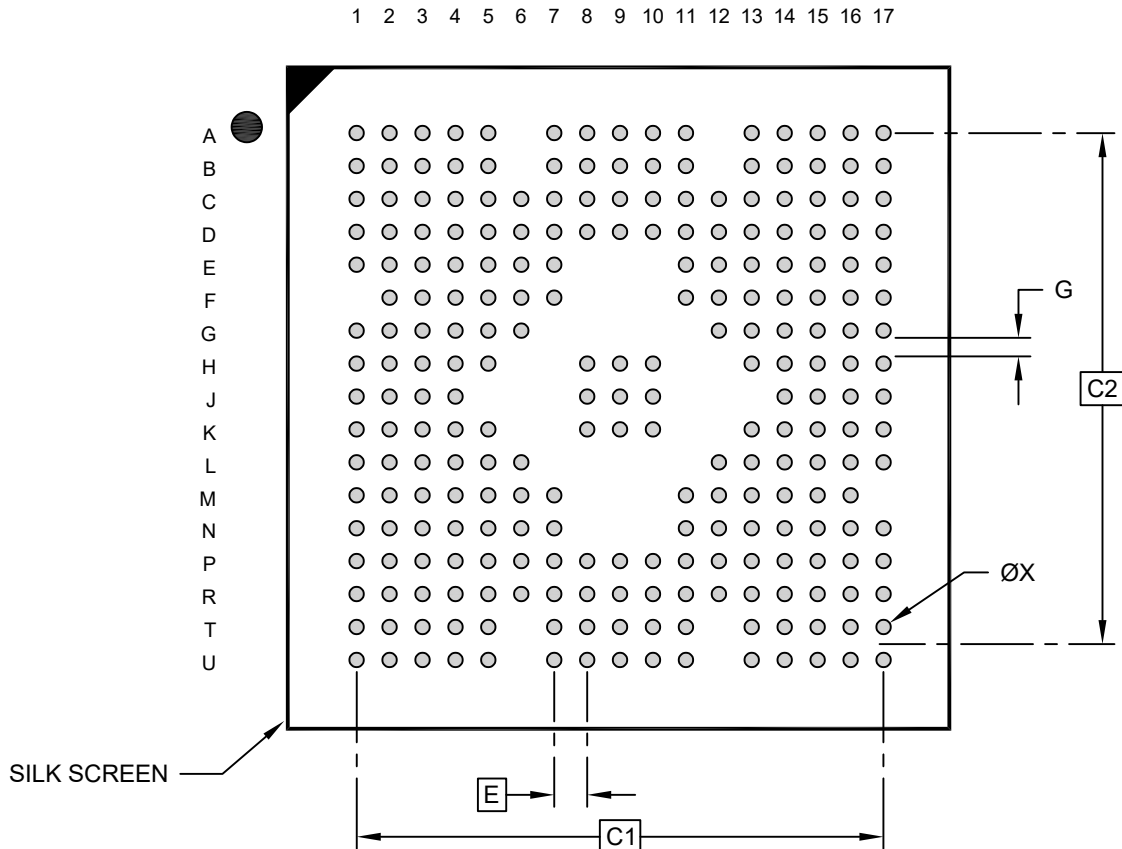


# 243-Ball Thin Fine-Pitch Ball Grid Array (4TB) - 16x16x1.23 mm Body [TFBGA]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1		12.80 BSC		
Contact Pad Spacing	C2		12.80 BSC		
Contact Pad Width (X243)	X				0.35
Contact Pad to Contact Pad	G		0.45		

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.